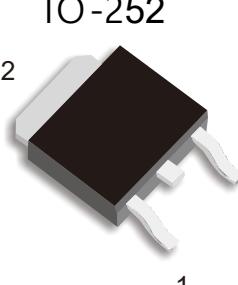
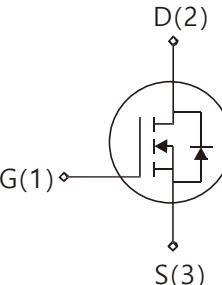


<h2>XXW5N65</h2> <p>Features:</p> <ul style="list-style-type: none"> <li><input type="checkbox"/> Low Intrinsic Capacitances.</li> <li><input type="checkbox"/> Excellent Switching Characteristics.</li> <li><input type="checkbox"/> Extended Safe Operating Area.</li> <li><input type="checkbox"/> Unrivalled Gate Charge :<math>Q_g = 14\text{nC}</math> (Typ.).</li> <li><input type="checkbox"/> <math>V_{DSS} = 650\text{V}</math>, <math>I_D = 5\text{A}</math></li> <li><input type="checkbox"/> <math>R_{DS(on)} : 2.50\Omega</math> (Max) @ <math>V_G = 10\text{V}</math></li> <li><input type="checkbox"/> 100% Avalanche Tested</li> </ul>	 <b>TO -252</b>  1.Gate (G) 2.Drain (D) 3.Source (S)
--	--

### Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	650	V
$I_D$	Drain Current	$T_j = 25^\circ\text{C}$	5.0
		$T_j = 100^\circ\text{C}$	2.7
$V_{GSS}$	Gate - Source voltage	30	V
$E_{AS}$	Single Pulse Avalanche Energy(note1)	120	mJ
$I_{AR}$	Avalanche Current (note2)	5.0	A
$P_D$	Power Dissipation ( $T_j = 25^\circ\text{C}$ )	50	W
$T_j$	Junction Temperature(Max)	150	°C
$T_{stg}$	Storage Temperature	-55~+150	°C
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	2.4	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient		62.5	°C/W

## Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250 μA , V <sub>GS</sub> =0	650	-	-	V
△BV <sub>DSS</sub> / △TJ	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250 μA , Reference to 25 °C	-	0.67	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V	-	-	10	μA
		V <sub>DS</sub> =520V, Tj=125°C			100	
I <sub>GSSF</sub>	Gate-body leakage Current, Forward	V <sub>GS</sub> =+30V, V <sub>DS</sub> =0V	-	-	100	nA
I <sub>GSSR</sub>	Gate-body leakage Current, Reverse	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V	-	-	-100	
On Characteristics						
V <sub>GS(TH)</sub>	Date Threshold Voltage	I <sub>D</sub> =250μA,V <sub>DS</sub> =V <sub>GS</sub>	2	-	4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	I <sub>D</sub> =2.0A,V <sub>GS</sub> =10V	-		2.5	Ω
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0 , f=1.0MHz	-	560	-	pF
C <sub>oss</sub>	Output Capacitance		-	48	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	5.4	-	
Switching Characteristics						
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =325V , I <sub>D</sub> =5A R <sub>G</sub> =25Ω (Note 3,4)	-	25		nS
T <sub>r</sub>	Turn-On Rise Time		-	45		
T <sub>d(off)</sub>	Turn-Off Delay Time		-	25		
T <sub>f</sub>	Turn-Off Rise Time		-	35		
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =520V,V <sub>GS</sub> =10V , I <sub>D</sub> =5A (Note3,4)	-	14 . 3		nC
Q <sub>gs</sub>	Gate-Source Charge		-	2.8	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	4.5	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I <sub>s</sub>	Max. Diode Forward Current	-		--	4	A
I <sub>SM</sub>	Max. Pulsed Forward Current	-		--	16	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>D</sub> =5A	-	-	1.4	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =5A, V <sub>GS</sub> =0V diF/dt=100A/μs (Note3)	-	393	-	nS
Q <sub>rr</sub>	Reverse Recovery Charge		-	1.5	-	μC

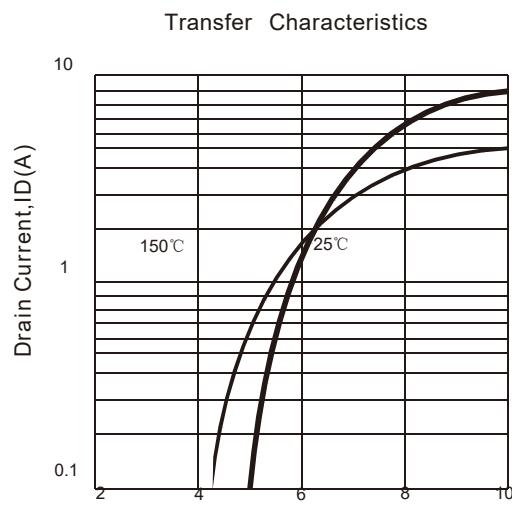
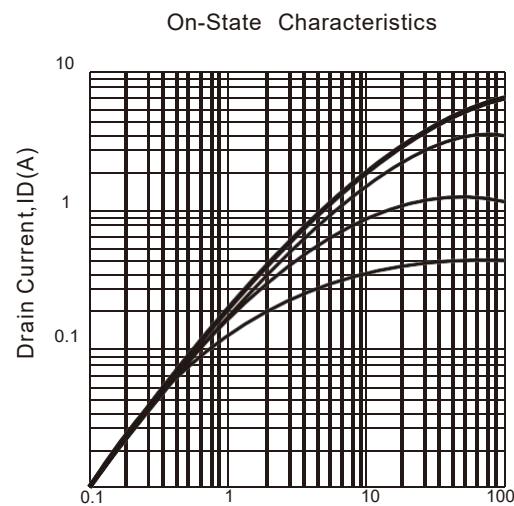
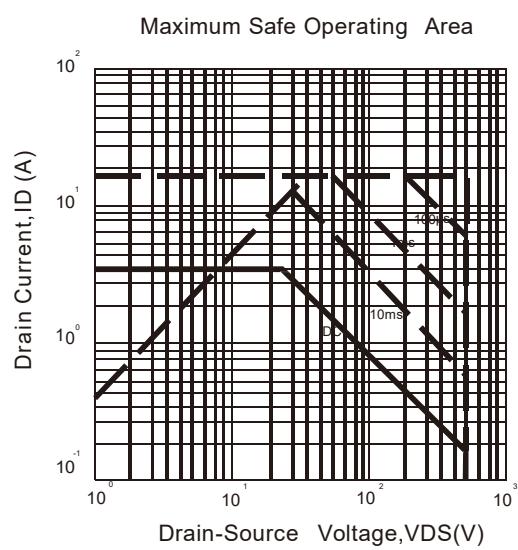
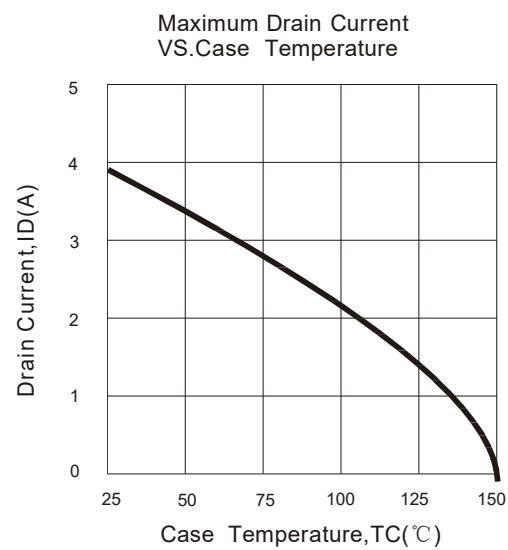
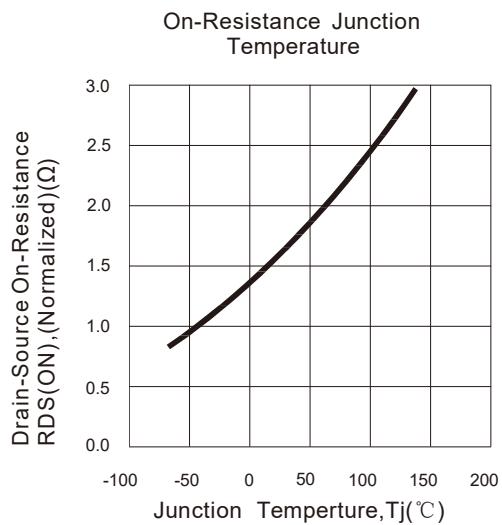
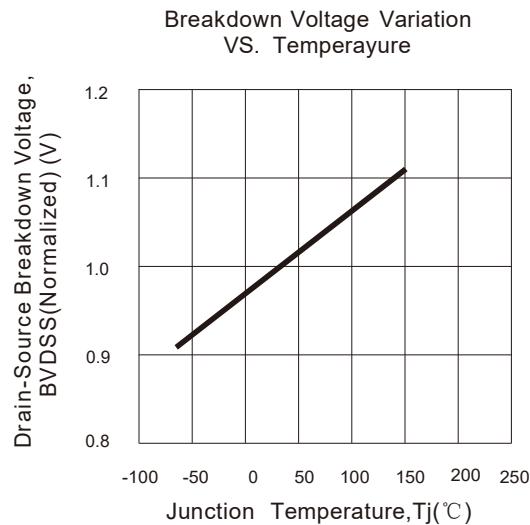
Notes : 1, L=0.5mH, IAS= 5A, VDD=50V, RG=25Ω , Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

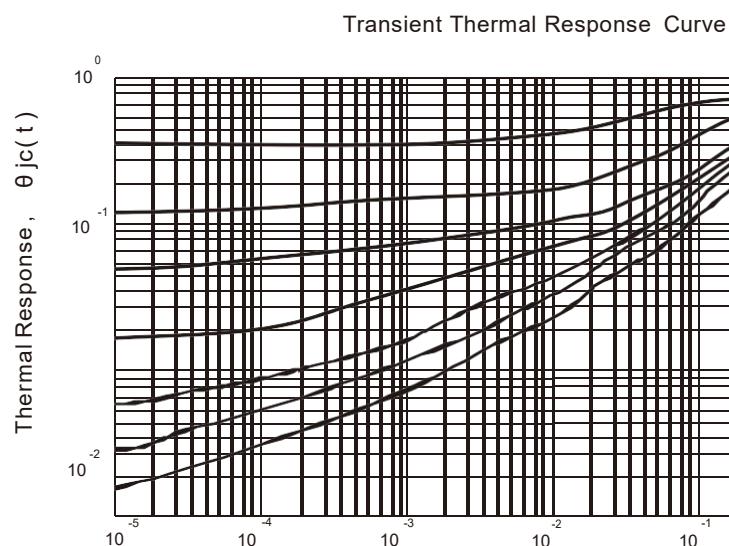
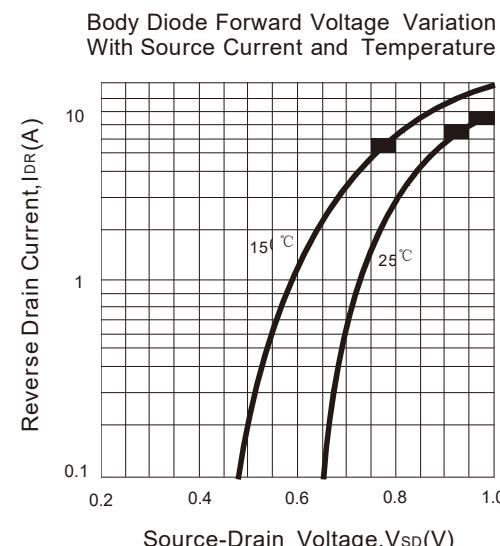
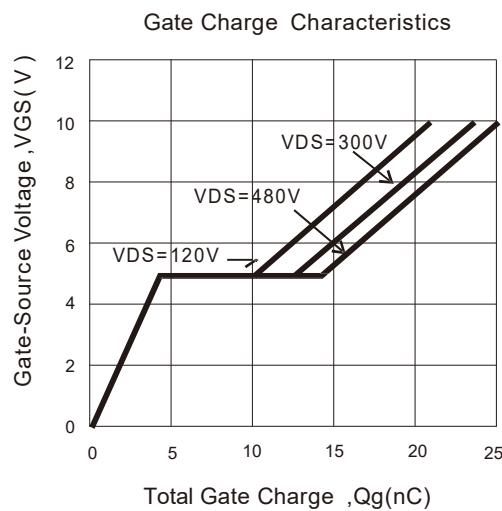
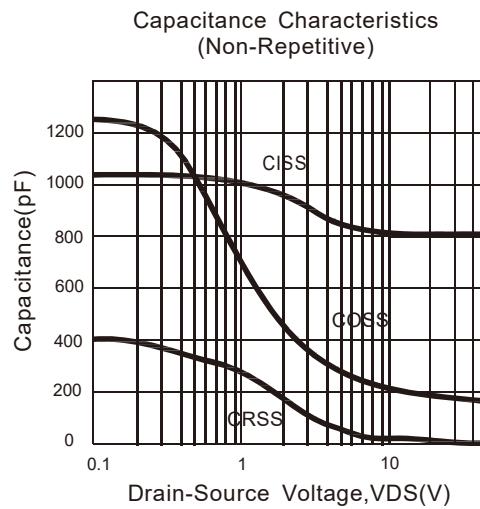
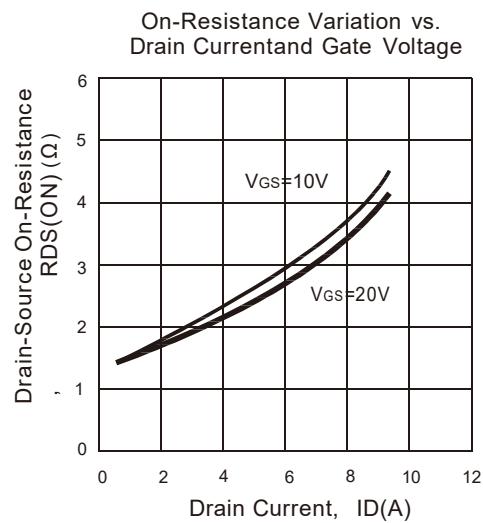
3, Pulse Test : Pulse Width ≤300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

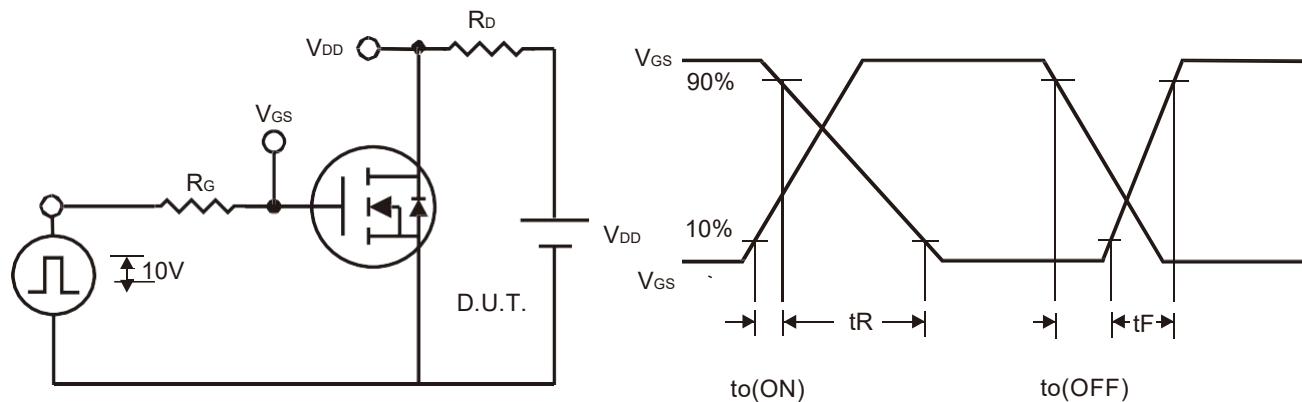
### Typical Characteristics



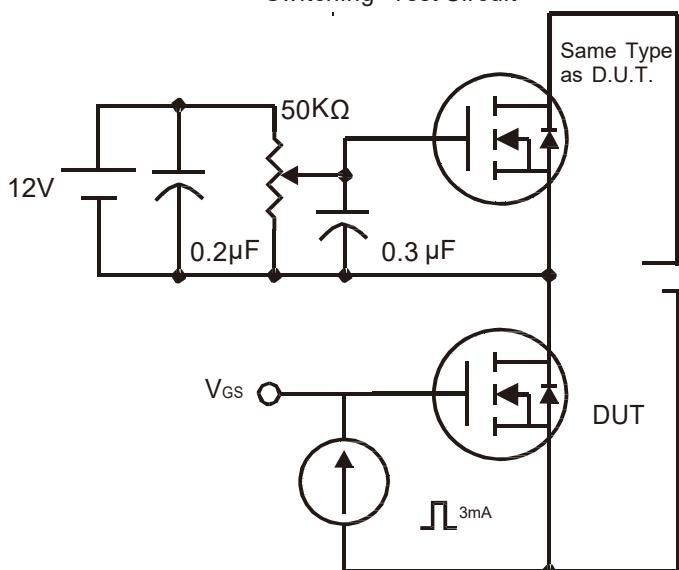
## Typical Characteristics (Continued)



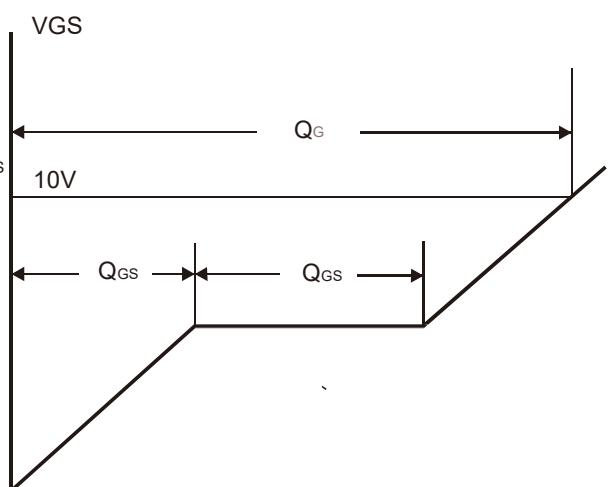
### Gate Charge Test Circuit & Waveform



Switching Test Circuit

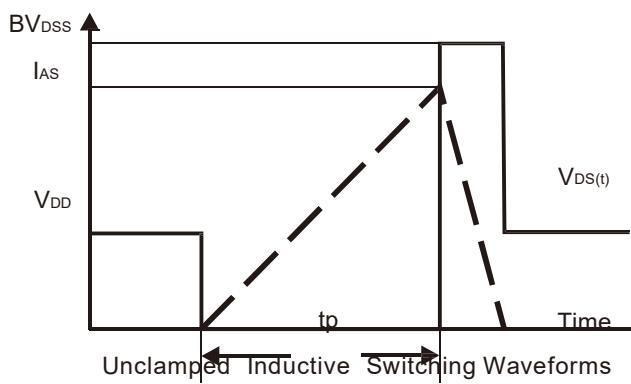
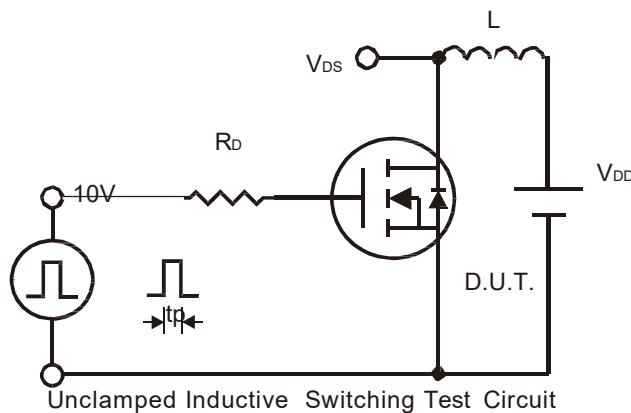


Switching Waveforms

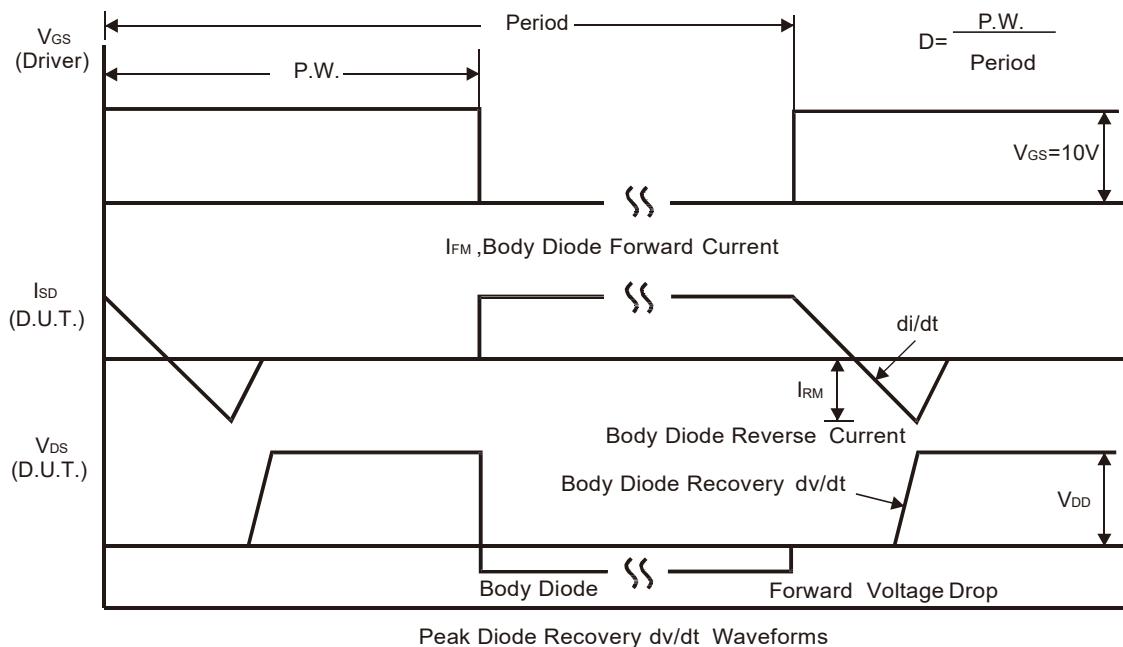
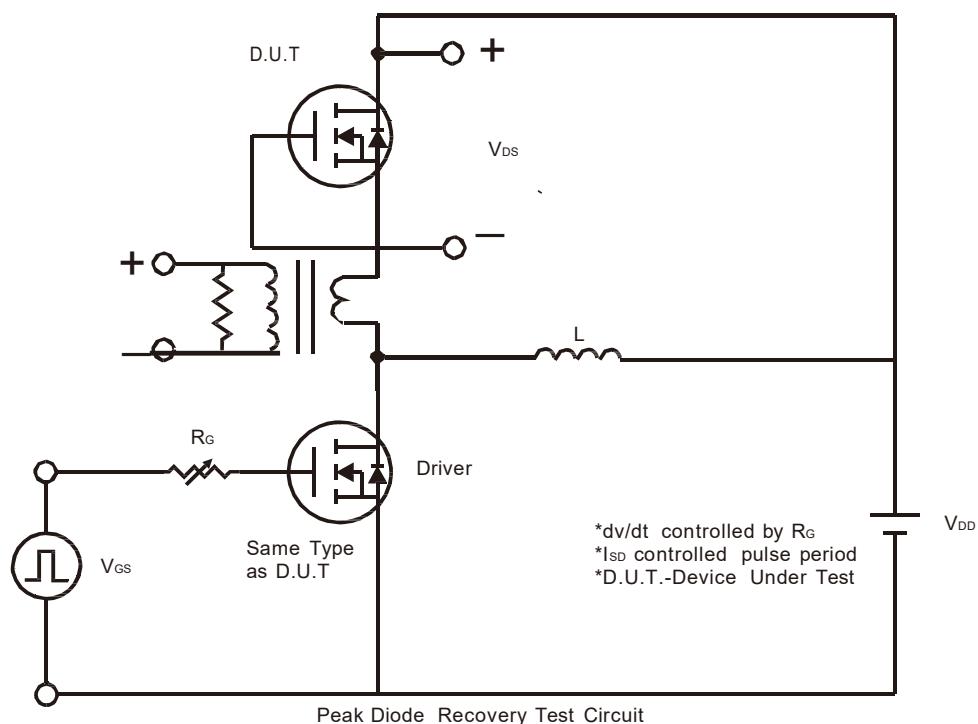


Gate Charge Test Circuit

Gate Charge Waveform



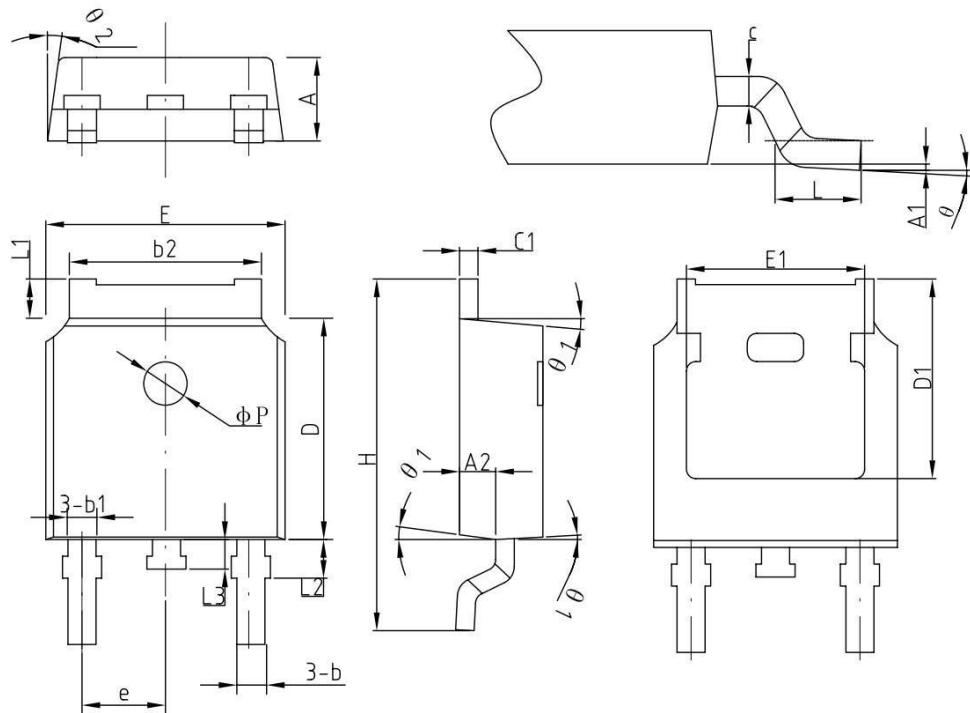
## Peak Diode Recovery dv/dt Test Circuit &amp; Waveform



## Package Dimension

## TO-252

Unit: mm


COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.2	2.30	2.38
A1	0	—	0.10
A2	0.90	1.01	1.10
b	0.71	0.76	0.86
b1		0.76	
b2	5.13	5.33	5.46
c	0.47	0.50	0.60
c1	0.47	0.50	0.60
D	6.0	6.10	6.20
D1	—	5.30	—
E	6.50	6.60	6.70
E1	—	4.80	—
e		2.286BSC	
H	9.70	10.10	10.40
L	1.40	1.50	1.70
L1	0.90	—	1.25
L2		1.05	
L3		0.8	
φP		1.2	
θ	0°	—	8°
θ 1	5°	7°	9°
θ 2	5°	7°	9°